

L Number	Hits	Search Text	DB	Time stamp
1	112	((((dielectric insulat\$3) and (hydrogen H2 "H.sub.2")) and (wet near10 (treat\$3 solution))) and ((dielectric insulat\$3) near100 (hydrogen H2 "H.sub.2") near100 (wet near10 (treat\$3 solution))))	USPAT; US-PGPUB	2004/09/29 18:19
2	40	((((dielectric insulat\$3) and (hydrogen H2 "H.sub.2")) and (wet near10 (treat\$3 solution))) and ((dielectric insulat\$3) near100 (hydrogen H2 "H.sub.2") near100 (wet near10 (treat\$3 solution)))) and (argon Ar)	USPAT; US-PGPUB	2004/09/29 18:19
3	10	((((dielectric insulat\$3) and (hydrogen H2 "H.sub.2")) and (wet near10 (treat\$3 solution))) and ((dielectric insulat\$3) near100 (hydrogen H2 "H.sub.2") near100 (wet near10 (treat\$3 solution))))	EPO; JPO; DERWENT; IBM_TDB	2004/09/29 18:19
5	0	((((dielectric insulat\$3) and (hydrogen H2 "H.sub.2")) and (wet near10 (treat\$3 solution))) and ((dielectric insulat\$3) near100 (hydrogen H2 "H.sub.2") near100 (wet near10 (treat\$3 solution)))) and (argon Ar)	EPO; JPO; DERWENT; IBM_TDB	2004/09/29 18:19
6	10279	(ILD (inter near5 dielectric) IMD)	USPAT; US-PGPUB	2004/09/29 18:39
7	3316	((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")	USPAT; US-PGPUB	2004/09/29 18:39
8	2351	((((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")) and (wet solution))	USPAT; US-PGPUB	2004/09/29 18:39
9	1440	((((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")) and (wet solution)) and (clean\$3 treat\$3))	USPAT; US-PGPUB	2004/09/29 18:21
10	942	(((((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")) and (wet solution)) and (clean\$3 treat\$3)) and plasma	USPAT; US-PGPUB	2004/09/29 18:21
11	523	(((((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")) and (wet solution)) and (clean\$3 treat\$3)) and plasma) and (argon "Ar")	USPAT; US-PGPUB	2004/09/29 18:22
12	332	((((((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")) and (wet solution)) and (clean\$3 treat\$3)) and plasma) and (argon "Ar")) and (resist PR photoresist)	USPAT; US-PGPUB	2004/09/29 18:22
13	327	((((((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")) and (wet solution)) and (clean\$3 treat\$3)) and plasma) and (argon "Ar")) and (resist PR photoresist)) and (etch\$3 pattern\$3)	USPAT; US-PGPUB	2004/09/29 18:23
14	2414	(ILD (inter near5 dielectric) IMD)	EPO; JPO; DERWENT; IBM_TDB	2004/09/29 18:39
15	86	((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")	EPO; JPO; DERWENT; IBM_TDB	2004/09/29 18:39
16	14	((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")) and (wet solution)	EPO; JPO; DERWENT; IBM_TDB	2004/09/29 18:40